

Product Change Notification - GBNG-07TJKP903

Date: 28 Nov 2017

Product Category: Real-Time Clock/Calendar; Temperature Sensors; 8-bit PIC Microcontrollers; Memory; Power Management - PWM Controllers; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Linear Op Amps; Instrumentation Amplifier

Notification subject: CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Notification text: **PCN Status:** Initial notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:
Assembled at MTAI assembly site.

Post Change:
Assembled at MTAI or MMT assembly site.

Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - Branch (MMT)	
Wire material	CuPdAu	CuPdAu	CuPdAu	
Die attach material	8390A	8390A	8390A	
Molding compound material	G600V	G600V	G600V	
Lead frame material	CDA194	CDA194	CDA194	

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying MMT as an additional assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2017					=	January 2018				
	44	45	46	47	48		01	02	03	04	05
Workweek											
Initial PCN Issue Date				X							
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
November 28, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_GBNG-07TJKP903_Affected CPN.pdf](#)
[PCN_GBNG-07TJKP903_Qual Plan.pdf](#)
[PCN_GBNG-07TJKP903_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
11AA010-I/MS
11AA010T-I/MS
11AA020-I/MS
11AA020T-I/MS
11AA040-I/MS
11AA040T-I/MS
11AA080-I/MS
11AA080T-I/MS
11AA160-I/MS
11AA160T-I/MS
11AA161-I/MS
11AA161T-I/MS
11LC010-E/MS
11LC010-I/MS
11LC010T-E/MS
11LC010T-I/MS
11LC020-E/MS
11LC020-I/MS
11LC020T-E/MS
11LC020T-I/MS
11LC040-E/MS
11LC040-I/MS
11LC040T-E/MS
11LC040T-I/MS
11LC080-E/MS
11LC080-I/MS
11LC080T-E/MS
11LC080T-I/MS
11LC160-E/MS
11LC160-I/MS
11LC160T-E/MS
11LC160T-I/MS
11LC161-E/MS
11LC161-I/MS
11LC161T-E/MS
11LC161T-I/MS
24AA014H-I/MS
24AA014HT-I/MS
24AA014-I/MS
24AA014T-I/MS
24AA01H-I/MS
24AA01HT-I/MS
24AA01-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
24AA01T-I/MS
24AA024H-I/MS
24AA024HT-I/MS
24AA024-I/MS
24AA024T-I/MS
24AA025-I/MS
24AA025T-I/MS
24AA02H-I/MS
24AA02HT-I/MS
24AA02-I/MS
24AA02-I/MSB31
24AA02T-I/MS
24AA02T-I/MSB31
24AA044-E/MS
24AA044-I/MS
24AA044T-E/MS
24AA044T-I/MS
24AA04H-I/MS
24AA04HT-I/MS
24AA04-I/MS
24AA04T-I/MS
24AA08H-I/MS
24AA08HT-I/MS
24AA08-I/MS
24AA08T-I/MS
24AA128-I/MS
24AA128T-I/MS
24AA16-E/MS
24AA16H-I/MS
24AA16HT-I/MS
24AA16-I/MS
24AA16T-E/MS
24AA16T-I/MS
24AA256-E/MS
24AA256-I/MS
24AA256-I/MSRVE
24AA256T-E/MS
24AA256T-I/MS
24AA256T-I/MSRVE
24AA32AF-I/MS
24AA32AFT-I/MS
24AA32A-I/MS
24AA32AT-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
24AA52-I/MS
24AA52T-I/MS
24AA64-E/MS
24AA64F-I/MS
24AA64FT-I/MS
24AA64-I/MS
24AA64T-E/MS
24AA64T-I/MS
24AA64T-I/MS028
24C01C-E/MS
24C01C-I/MS
24C01CT-E/MS
24C01CT-I/MS
24C02C-E/MS
24C02C-I/MS
24C02CT-E/MS
24C02CT-I/MS
24FC128-I/MS
24FC128T-I/MS
24FC256-I/MS
24FC256T-I/MS
24FC64F-I/MS
24FC64FT-I/MS
24FC64-I/MS
24FC64T-I/MS
24LC014-E/MS
24LC014H-E/MS
24LC014H-I/MS
24LC014HT-E/MS
24LC014HT-I/MS
24LC014-I/MS
24LC014T-E/MS
24LC014T-I/MS
24LC01B-E/MS
24LC01BH-E/MS
24LC01BH-I/MS
24LC01BHT-E/MS
24LC01BHT-I/MS
24LC01B-I/MS
24LC01BT-E/MS
24LC01BT-I/MS
24LC024-E/MS
24LC024H-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
24LC024H-I/MS
24LC024HT-E/MS
24LC024HT-I/MS
24LC024-I/MS
24LC024T-E/MS
24LC024T-I/MS
24LC025-E/MS
24LC025-I/MS
24LC025T-E/MS
24LC025T-I/MS
24LC02B-E/MS
24LC02BH-E/MS
24LC02BH-I/MS
24LC02BHT-E/MS
24LC02BHT-I/MS
24LC02B-I/MS
24LC02BT-E/MS
24LC02BT-I/MS
24LC04B-E/MS
24LC04BH-E/MS
24LC04BH-I/MS
24LC04BHT-E/MS
24LC04BHT-I/MS
24LC04B-I/MS
24LC04BT-E/MS
24LC04BT-I/MS
24LC08B-E/MS
24LC08BH-E/MS
24LC08BH-I/MS
24LC08BHT-E/MS
24LC08BHT-I/MS
24LC08B-I/MS
24LC08BT-E/MS
24LC08BT-I/MS
24LC128-E/MS
24LC128-I/MS
24LC128T-E/MS
24LC128T-I/MS
24LC16B-E/MS
24LC16BH-E/MS
24LC16BH-I/MS
24LC16BHT-E/MS
24LC16BHT-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
24LC16B-I/MS
24LC16BT-E/MS
24LC16BT-I/MS
24LC256-E/MS
24LC256-I/MS
24LC256-I/MSRVF
24LC256T-E/MS
24LC256T-I/MS
24LC256T-I/MSRVF
24LC32A-E/MS
24LC32AF-E/MS
24LC32AF-I/MS
24LC32AFT-E/MS
24LC32AFT-I/MS
24LC32A-I/MS
24LC32AT-E/MS
24LC32AT-I/MS
24LC64-E/MS
24LC64F-E/MS
24LC64F-I/MS
24LC64FT-E/MS
24LC64FT-I/MS
24LC64-I/MS
24LC64T-E/MS
24LC64T-I/MS
24LCS52-I/MS
24LCS52T-I/MS
24VL014/MS
24VL014H/MS
24VL014HT/MS
24VL014T/MS
24VL024/MS
24VL024H/MS
24VL024HT/MS
24VL024T/MS
24VL025/MS
24VL025T/MS
25AA010A-I/MS
25AA010AT-I/MS
25AA020A-I/MS
25AA020AT-I/MS
25AA040A-I/MS
25AA040AT-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
25AA080A-I/MS
25AA080AT-I/MS
25AA080B-I/MS
25AA080BT-I/MS
25AA080C-I/MS
25AA080CT-I/MS
25AA080D-I/MS
25AA080DT-I/MS
25AA160A-I/MS
25AA160AT-I/MS
25AA160B-I/MS
25AA160BT-I/MS
25AA160C-I/MS
25AA160CT-I/MS
25AA160D-E/MS
25AA160D-I/MS
25AA160DT-E/MS
25AA160DT-I/MS
25AA320A-I/MS
25AA320AT-I/MS
25AA640A-E/MS
25AA640A-I/MS
25AA640AT-E/MS
25AA640AT-I/MS
25LC010A-E/MS
25LC010A-I/MS
25LC010AT-E/MS
25LC010AT-I/MS
25LC020A-E/MS
25LC020A-I/MS
25LC020AT-E/MS
25LC020AT-I/MS
25LC040A-E/MS
25LC040A-I/MS
25LC040AT-E/MS
25LC040AT-I/MS
25LC080A-E/MS
25LC080A-I/MS
25LC080AT-E/MS
25LC080AT-I/MS
25LC080B-E/MS
25LC080B-I/MS
25LC080BT-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
25LC080BT-I/MS
25LC080C-E/MS
25LC080C-I/MS
25LC080CT-E/MS
25LC080CT-I/MS
25LC080D-E/MS
25LC080D-I/MS
25LC080DT-E/MS
25LC080DT-I/MS
25LC160A-E/MS
25LC160A-I/MS
25LC160AT-E/MS
25LC160AT-I/MS
25LC160B-E/MS
25LC160B-I/MS
25LC160BT-E/MS
25LC160BT-I/MS
25LC160C-E/MS
25LC160C-I/MS
25LC160CT-E/MS
25LC160CT-I/MS
25LC160D-E/MS
25LC160D-I/MS
25LC160DT-E/MS
25LC160DT-I/MS
25LC320A-E/MS
25LC320A-I/MS
25LC320AT-E/MS
25LC320AT-I/MS
25LC640A-E/MS
25LC640A-I/MS
25LC640AT-E/MS
25LC640AT-I/MS
34AA02-E/MS
34AA02-I/MS
34AA02T-E/MS
34AA02T-I/MS
34LC02-E/MS
34LC02-I/MS
34LC02T-E/MS
34LC02T-I/MS
34VL02/MS
34VL02T/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
93AA46A-I/MS
93AA46AT-I/MS
93AA46B-I/MS
93AA46BT-I/MS
93AA46C-I/MS
93AA46CT-I/MS
93AA56A-I/MS
93AA56AT-I/MS
93AA56B-I/MS
93AA56BT-I/MS
93AA56C-I/MS
93AA56CT-I/MS
93AA66A-I/MS
93AA66AT-I/MS
93AA66B-I/MS
93AA66B-I/MSL21
93AA66BT-I/MS
93AA66BT-I/MSL21
93AA66C-I/MS
93AA66CT-I/MS
93AA76A-I/MS
93AA76AT-I/MS
93AA76B-I/MS
93AA76BT-I/MS
93AA76C-I/MS
93AA76CT-I/MS
93AA86A-I/MS
93AA86AT-I/MS
93AA86B-I/MS
93AA86BT-I/MS
93AA86C-I/MS
93AA86CT-I/MS
93C46A-E/MS
93C46A-I/MS
93C46AT-E/MS
93C46AT-I/MS
93C46B-E/MS
93C46B-I/MS
93C46BT-E/MS
93C46BT-I/MS
93C46C-E/MS
93C46C-I/MS
93C46CT-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
93C46CT-I/MS
93C56A-E/MS
93C56A-I/MS
93C56AT-E/MS
93C56AT-I/MS
93C56B-E/MS
93C56B-I/MS
93C56BT-E/MS
93C56BT-I/MS
93C56C-E/MS
93C56C-I/MS
93C56CT-E/MS
93C56CT-I/MS
93C66A-E/MS
93C66A-I/MS
93C66AT-E/MS
93C66AT-I/MS
93C66B-E/MS
93C66B-I/MS
93C66BT-E/MS
93C66BT-I/MS
93C66C-E/MS
93C66C-I/MS
93C66CT-E/MS
93C66CT-I/MS
93C76A-E/MS
93C76A-I/MS
93C76AT-E/MS
93C76AT-I/MS
93C76B-E/MS
93C76B-I/MS
93C76BT-E/MS
93C76BT-I/MS
93C76C-E/MS
93C76C-I/MS
93C76CT-E/MS
93C76CT-I/MS
93C86A-E/MS
93C86A-I/MS
93C86AT-E/MS
93C86AT-I/MS
93C86B-E/MS
93C86B-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
93C86BT-E/MS
93C86BT-I/MS
93C86C-E/MS
93C86C-I/MS
93C86CT-E/MS
93C86CT-I/MS
93LC46A-E/MS
93LC46A-I/MS
93LC46AT-E/MS
93LC46AT-I/MS
93LC46B-E/MS
93LC46B-I/MS
93LC46BT-E/MS
93LC46BT-I/MS
93LC46C-E/MS
93LC46C-I/MS
93LC46CT-E/MS
93LC46CT-I/MS
93LC56A-E/MS
93LC56A-I/MS
93LC56AT-E/MS
93LC56AT-I/MS
93LC56B-E/MS
93LC56B-I/MS
93LC56BT-E/MS
93LC56BT-I/MS
93LC56C-E/MS
93LC56C-I/MS
93LC56CT-E/MS
93LC56CT-I/MS
93LC66A-E/MS
93LC66A-I/MS
93LC66AT-E/MS
93LC66AT-I/MS
93LC66B-E/MS
93LC66B-I/MS
93LC66BT-E/MS
93LC66BT-I/MS
93LC66C-E/MS
93LC66C-I/MS
93LC66CT-E/MS
93LC66CT-I/MS
93LC76A-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
93LC76A-I/MS
93LC76AT-E/MS
93LC76AT-I/MS
93LC76B-E/MS
93LC76B-I/MS
93LC76BT-E/MS
93LC76BT-I/MS
93LC76C-E/MS
93LC76C-I/MS
93LC76CT-E/MS
93LC76CT-I/MS
93LC86A-E/MS
93LC86A-I/MS
93LC86AT-E/MS
93LC86AT-I/MS
93LC86B-E/MS
93LC86B-I/MS
93LC86BT-E/MS
93LC86BT-I/MS
93LC86C-E/MS
93LC86C-I/MS
93LC86CT-E/MS
93LC86CT-I/MS
MCP1632-AAE/MS
MCP1632-BAE/MS
MCP1632T-AAE/MS
MCP1632T-BAE/MS
MCP3422A0-E/MS
MCP3422A0T-E/MS
MCP3422A1-E/MS
MCP3422A1T-E/MS
MCP3422A2-E/MS
MCP3422A2T-E/MS
MCP3422A3-E/MS
MCP3422A3T-E/MS
MCP3422A4-E/MS
MCP3422A4T-E/MS
MCP3422A5-E/MS
MCP3422A5T-E/MS
MCP3422A6-E/MS
MCP3422A6T-E/MS
MCP3422A7-E/MS
MCP3422A7T-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP3426A0-E/MS
MCP3426A0T-E/MS
MCP3426A1-E/MS
MCP3426A1T-E/MS
MCP3426A2-E/MS
MCP3426A2T-E/MS
MCP3426A3-E/MS
MCP3426A3T-E/MS
MCP3426A4-E/MS
MCP3426A4T-E/MS
MCP3426A5-E/MS
MCP3426A5T-E/MS
MCP3426A6-E/MS
MCP3426A6T-E/MS
MCP3426A7-E/MS
MCP3426A7T-E/MS
MCP3550-50E/MS
MCP3550-60E/MS
MCP3550T-50E/MS
MCP3550T-60E/MS
MCP3551-E/MS
MCP3551T-E/MS
MCP3553-E/MS
MCP3553T-E/MS
MCP4011-103E/MS
MCP4011-202E/MS
MCP4011-502E/MS
MCP4011-503E/MS
MCP4011T-103E/MS
MCP4011T-202E/MS
MCP4011T-502E/MS
MCP4011T-503E/MS
MCP4021-103E/MS
MCP4021-202E/MS
MCP4021-502E/MS
MCP4021-503E/MS
MCP4021T-103E/MS
MCP4021T-202E/MS
MCP4021T-502E/MS
MCP4021T-503E/MS
MCP4131-103E/MS
MCP4131-104E/MS
MCP4131-502E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP4131-503E/MS
MCP4131T-103E/MS
MCP4131T-104E/MS
MCP4131T-502E/MS
MCP4131T-503E/MS
MCP4132-103E/MS
MCP4132-104E/MS
MCP4132-502E/MS
MCP4132-503E/MS
MCP4132T-103E/MS
MCP4132T-104E/MS
MCP4132T-502E/MS
MCP4132T-503E/MS
MCP4141-103E/MS
MCP4141-104E/MS
MCP4141-502E/MS
MCP4141-503E/MS
MCP4141T-103E/MS
MCP4141T-104E/MS
MCP4141T-502E/MS
MCP4141T-503E/MS
MCP4142-103E/MS
MCP4142-104E/MS
MCP4142-502E/MS
MCP4142-503E/MS
MCP4142T-103E/MS
MCP4142T-104E/MS
MCP4142T-502E/MS
MCP4142T-503E/MS
MCP4151-103E/MS
MCP4151-104E/MS
MCP4151-502E/MS
MCP4151-503E/MS
MCP4151T-103E/MS
MCP4151T-104E/MS
MCP4151T-502E/MS
MCP4151T-503E/MS
MCP4152-103E/MS
MCP4152-104E/MS
MCP4152-502E/MS
MCP4152-503E/MS
MCP4152T-103E/MS
MCP4152T-104E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP4152T-502E/MS
MCP4152T-503E/MS
MCP4161-103E/MS
MCP4161-104E/MS
MCP4161-502E/MS
MCP4161-503E/MS
MCP4161T-103E/MS
MCP4161T-104E/MS
MCP4161T-502E/MS
MCP4161T-503E/MS
MCP4162-103E/MS
MCP4162-104E/MS
MCP4162-502E/MS
MCP4162-503E/MS
MCP4162T-103E/MS
MCP4162T-104E/MS
MCP4162T-502E/MS
MCP4162T-503E/MS
MCP4531-103E/MS
MCP4531-104E/MS
MCP4531-502E/MS
MCP4531-503E/MS
MCP4531T-103E/MS
MCP4531T-104E/MS
MCP4531T-502E/MS
MCP4531T-503E/MS
MCP4532-103E/MS
MCP4532-104E/MS
MCP4532-502E/MS
MCP4532-503E/MS
MCP4532T-103E/MS
MCP4532T-104E/MS
MCP4532T-502E/MS
MCP4532T-503E/MS
MCP4541-103E/MS
MCP4541-104E/MS
MCP4541-502E/MS
MCP4541-503E/MS
MCP4541T-103E/MS
MCP4541T-104E/MS
MCP4541T-502E/MS
MCP4541T-503E/MS
MCP4542-103E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP4542-104E/MS
MCP4542-502E/MS
MCP4542-503E/MS
MCP4542T-103E/MS
MCP4542T-104E/MS
MCP4542T-502E/MS
MCP4542T-503E/MS
MCP4551-103E/MS
MCP4551-104E/MS
MCP4551-502E/MS
MCP4551-503E/MS
MCP4551T-103E/MS
MCP4551T-104E/MS
MCP4551T-502E/MS
MCP4551T-503E/MS
MCP4552-103E/MS
MCP4552-104E/MS
MCP4552-502E/MS
MCP4552-503E/MS
MCP4552T-103E/MS
MCP4552T-104E/MS
MCP4552T-502E/MS
MCP4552T-503E/MS
MCP4561-103E/MS
MCP4561-104E/MS
MCP4561-502E/MS
MCP4561-503E/MS
MCP4561T-103E/MS
MCP4561T-104E/MS
MCP4561T-502E/MS
MCP4561T-503E/MS
MCP4562-103E/MS
MCP4562-104E/MS
MCP4562-502E/MS
MCP4562-503E/MS
MCP4562T-103E/MS
MCP4562T-104E/MS
MCP4562T-502E/MS
MCP4562T-503E/MS
MCP4801-E/MS
MCP4801T-E/MS
MCP4802-E/MS
MCP4802T-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP4811-E/MS
MCP4811T-E/MS
MCP4812-E/MS
MCP4812T-E/MS
MCP4821-E/MS
MCP4821T-E/MS
MCP4822-E/MS
MCP4822T-E/MS
MCP4901-E/MS
MCP4901T-E/MS
MCP4911-E/MS
MCP4911T-E/MS
MCP4921-E/MS
MCP4921T-E/MS
MCP6422-E/MS
MCP6422T-E/MS
MCP6472-E/MS
MCP6472T-E/MS
MCP6482-E/MS
MCP6482T-E/MS
MCP6492-E/MS
MCP6492T-E/MS
MCP6N16-001E/MS
MCP6N16-010E/MS
MCP6N16-100E/MS
MCP6N16T-001E/MS
MCP6N16T-010E/MS
MCP6N16T-100E/MS
MCP6V12-E/MS
MCP6V12T-E/MS
MCP6V32-E/MS
MCP6V32T-E/MS
MCP6V62-E/MS
MCP6V62T-E/MS
MCP6V72-E/MS
MCP6V72T-E/MS
MCP6V82-E/MS
MCP6V82T-E/MS
MCP6V92-E/MS
MCP6V92T-E/MS
MCP79400-I/MS
MCP79400T-I/MS
MCP79401-I/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
MCP79401T-I/MS
MCP79402-I/MS
MCP79402T-I/MS
MCP7940M-I/MS
MCP7940MT-I/MS
MCP7940N-E/MS
MCP7940N-I/MS
MCP7940NT-E/MS
MCP7940NT-I/MS
MCP79410-I/MS
MCP79410T-I/MS
MCP79411-I/MS
MCP79411T-I/MS
MCP79412-I/MS
MCP79412T-I/MS
MCP9801-M/MS
MCP9801-M/MSRC2
MCP9801T-M/MS
MCP9801T-M/MSRC2
MCP9803-M/MS
MCP9803-M/MSRC2
MCP9803T-M/MS
MCP9803T-M/MSRC2
MCP9804-E/MS
MCP9804-E/MSBBB
MCP9804T-E/MS
MCP9804T-E/MSBBB
MCP9808-E/MS
MCP9808T-E/MS
PIC12F508-E/MS
PIC12F508-I/MS
PIC12F508T-E/MS
PIC12F508T-I/MS
PIC12F508T-I/MS054
PIC12F508T-I/MS064
PIC12F508T-I/MS076
PIC12F508T-I/MS077
PIC12F509-E/MS
PIC12F509-I/MS
PIC12F509T-E/MS
PIC12F509T-I/MS
PIC12F509T-I/MS029
PIC12F510-E/MS

GBNG-07TJKP903_CCB 3178 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-07TJKP903
CATALOG_PART_NBR
PIC12F510-I/MS
PIC12F510-I/MS04
PIC12F510T-E/MS
PIC12F510T-I/MS
PIC12F519-E/MS
PIC12F519-I/MS
PIC12F519T-I/MS
PIC12F609-E/MS
PIC12F609-I/MS
PIC12F609T-E/MS
PIC12F609T-I/MS
PIC12F615-E/MS
PIC12F615-H/MS
PIC12F615-I/MS
PIC12F615-I/MS02
PIC12F615T-E/MS
PIC12F615T-H/MS
PIC12F615T-I/MS
PIC12F615T-I/MS059
PIC12F615T-I/MS063
PIC12F615T-I/MS068
PIC12F615T-I/MS080
PIC12F617-E/MS
PIC12F617-I/MS
PIC12F617-I/MS04
PIC12F617T-E/MS
PIC12F617T-I/MS
PIC12F617T-I/MS046
PIC12F617T-I/MS056
PIC12F617T-I/MS04
PIC12F617T-I/MSV01
PIC12HV609-E/MS
PIC12HV609-I/MS
PIC12HV609T-I/MS
PIC12HV615-E/MS
PIC12HV615-I/MS
PIC12HV615T-E/MS
PIC12HV615T-I/MS
TCN75AVUA
TCN75AVUA713



MICROCHIP

QUALIFICATION PLAN SUMMARY

PCN #: GBNG-07TJKP903

Date:

Nov 02, 2017

Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using palladium coated copper with gold flash (CuPdAu) bond wire.

Purpose: Qualification of MMT as an additional assembly site for selected products of the 150K and 160K wafer technologies available in 8L MSOP package using palladium coated copper with gold flash (CuPdAu) bond wire.

CCB: 3178

		Qualification Report
<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-001548/A
	MP Code (MPC)	DE0664A3XB04
	Part Number (CPN)	PIC12F617-E/MS
<u>Lead-Frame</u>	Paddle size	82x94 mils
	Material	CDA194
	Surface	Bare Cu
	Treatment	BOT
	Process	Stamped
	Lead-lock	No
	Part Number	10100839
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	8390A
	Conductive	Yes
<u>MC</u>	Part Number	G600V
<u>PKG</u>	PKG Type	MSOP
	Pin/Ball Count	8
	PKG width/size	3x3mm
<u>Die</u>	Die Thickness	8 mils
	Die Size	77.4x59.0 mils
	Fab Process (site)	160K/MCHP

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002 ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MTAI	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Backward Solderability	J-STD-002 ;Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.	22	5	1	27	> 95% lead coverage	5	MTAI	
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15		5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	MTAI	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
HTSL (High Temp Storage Life)	+175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp.85°C. 1 lot to be tested at 125C	45	5	1	50	0	25	MTAI	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. 1 lot to be tested at 125C	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. 1 lot to be tested at 125C	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.